



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

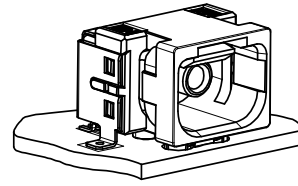
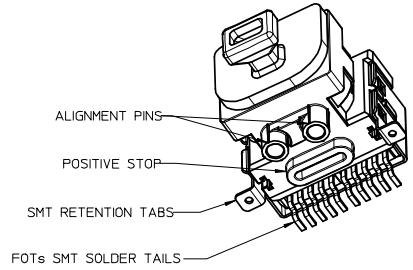
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

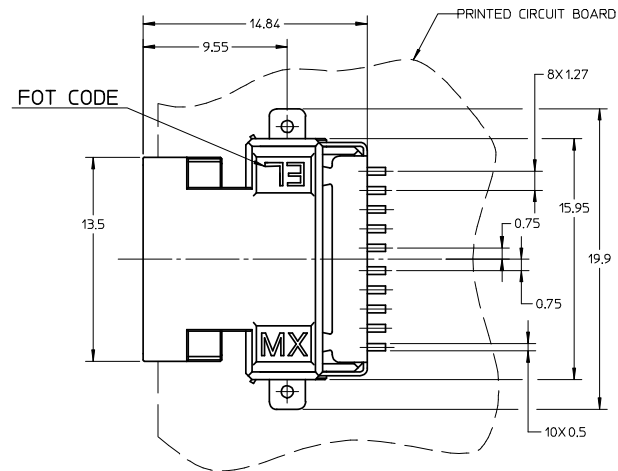


SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082200	IEEE-1394/ DIGITAL FDL300K	IE
1061083200	10/100 ETHERNET EDL300K	EL
1061084200	INDUSTRIAL DATA LINK IDL300K	ID

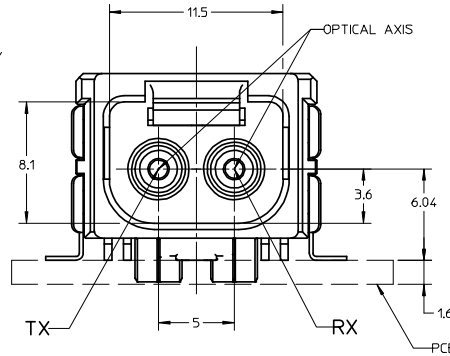
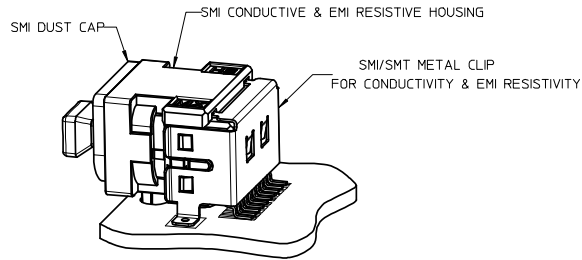


DUST CAP NOT SHOWN

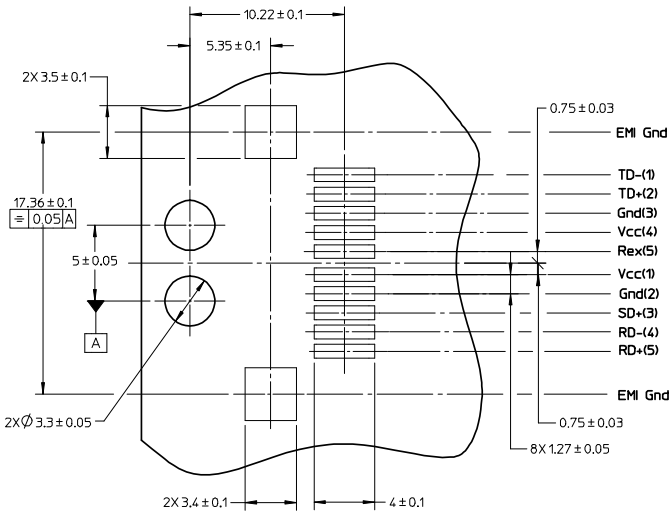
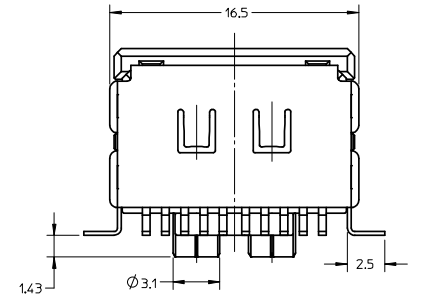
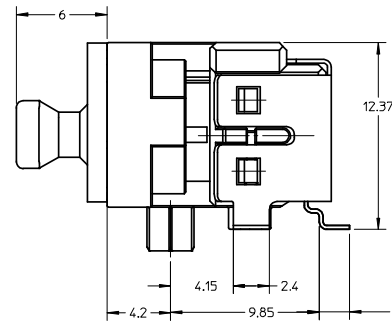
ISOMETRIC VIEWS
SCALE 2.5:1



DUST CAP NOT SHOWN



SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT

NOTE:
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
2. ATTACHMENT OF THE COMPONENT TO THE PCB SHALL BE VIA HOT BAR, LASER OR IR SOLDERING.
RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2008-0555 DRWN:SMIGO 2008/06/11 CHKD: 2008/06/11 APPR:SMIGO 2008/06/26	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	mm INCH ± --- ± --- ± --- ± --- ± --- ± ---	DRAWN BY BG 09/12/06	DATE 09/12/06	TITLE SMI TRANSCEIVER ASSEMBLY SURFACE MOUNT SOLDERING	
REV B	DESCRIPTION DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY SE 9/15/06		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-106108-X200	SHEET NO. 1 OF 1	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					